

Product Manufactory Notification

Issue Date: Nov 5, 2018

Notification Type:

Adding Assembly Site ASEKH estimate starting in February 2019.

Parts Affected:

Part Number	On Datasheet
BCM8836x	YES
BCM8846x	YES
BCM8856x	YES
BCM8866x	YES
BCM8835x	YES
BCM8855x	YES
BCM8865x	YES

Description and Extent of the Notification:

Adding assembly site for capacity management.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification has been performed on representative products to insure normal parametric distribution, consistent electrical performance, and reliability.

Assembly Site	ASEKH
Package Total Height	3.971mm

Broadcom Inc. reserves the right to manage assembly sites.

Qualification:

Qualification data has been generated and approved under FCBGA+SR 52.5mm x 52.5mm package as shown in table below.

PROCESS TECHNOLOGY	40nm
PACKAGE TYPE	FCBGA+SR, 52.5mm x 52.5mm
FOUNDY SOURCE	TSMC
ASSEMBLY SOURCE	ASE

TEST	SPEC	Conditions	Sample Size	Read point (hrs/cycles ~)	Results
Preconditioning	JESD-A113	Level 4(30°C, 60%RH)	154	96 Hrs	Pass
uHAST	JESD22-A118	130°C, 85% RH, No bias (pre-con parts)	77	96 Hrs	Pass
TC	JESD22-A104	-55°C to 125°C air to air (pre-con parts)	77	500 cycles	Pass
				700 cycles	Pass
				1000 cycles	Pass
HTSL	JESD22-A103	Ta= 150°C.	77	500 Hrs	Pass
				1000 Hrs	Pass

Please contact your Broadcom Inc. field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.